

ABSTRACT OF THE DISCLOSURE

Paste comprising metallic organic compound, in particular, gold-based metallic organic compound is used as a conductive material for repairing open defects in a metal pattern. After applying the paste, the paste is baked to deposit a metal film. This can produce a very thin metallic film having low electric resistance. Further, a semiconductor laser is used as a heating unit to heat only the paste applied to the open defect. A heating profile having a multi-step baking process includes a provisional baking and main baking process followed by a cooling process to produce a high-quality thin metallic film having no cracks and a dense texture.